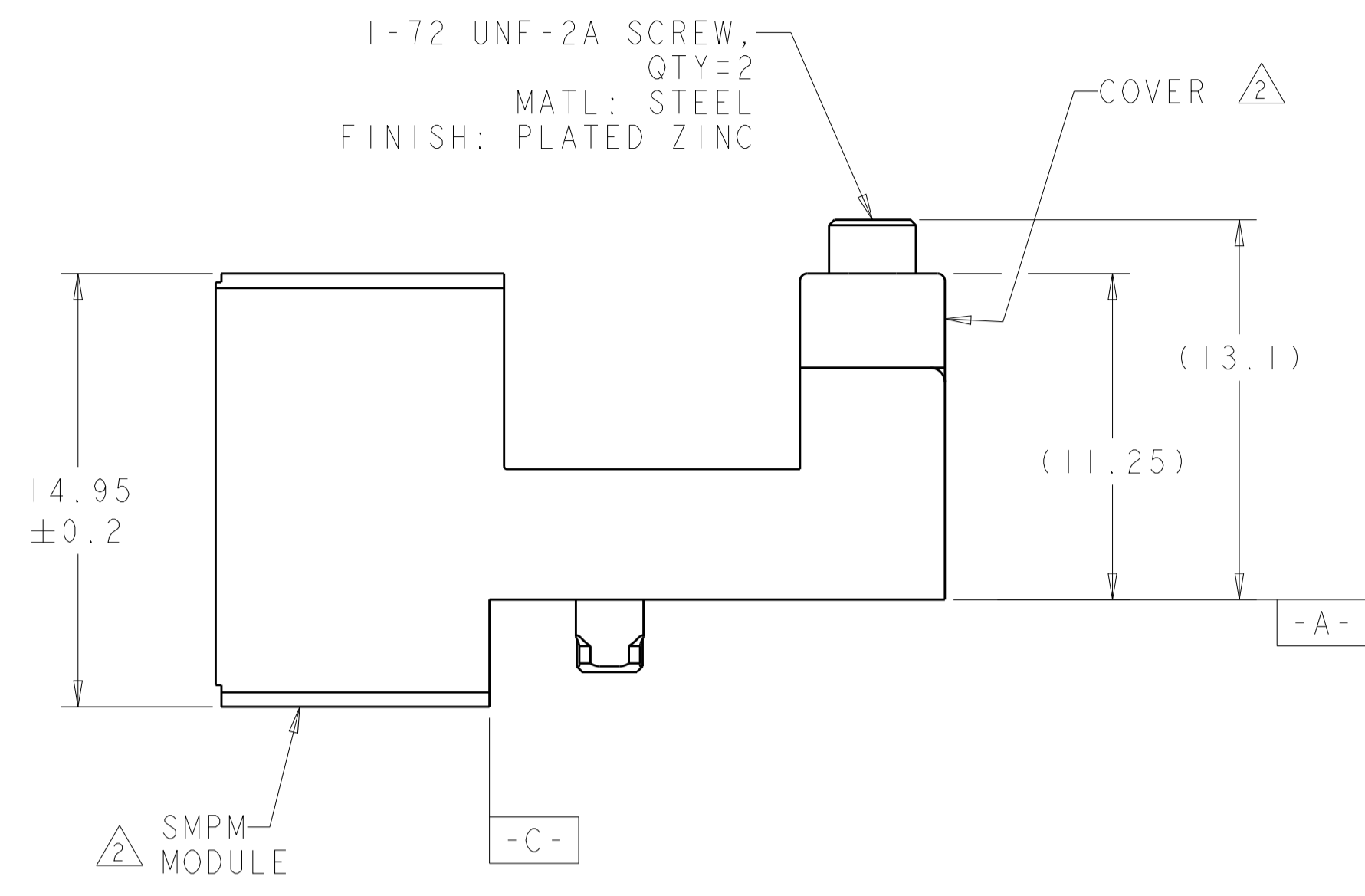
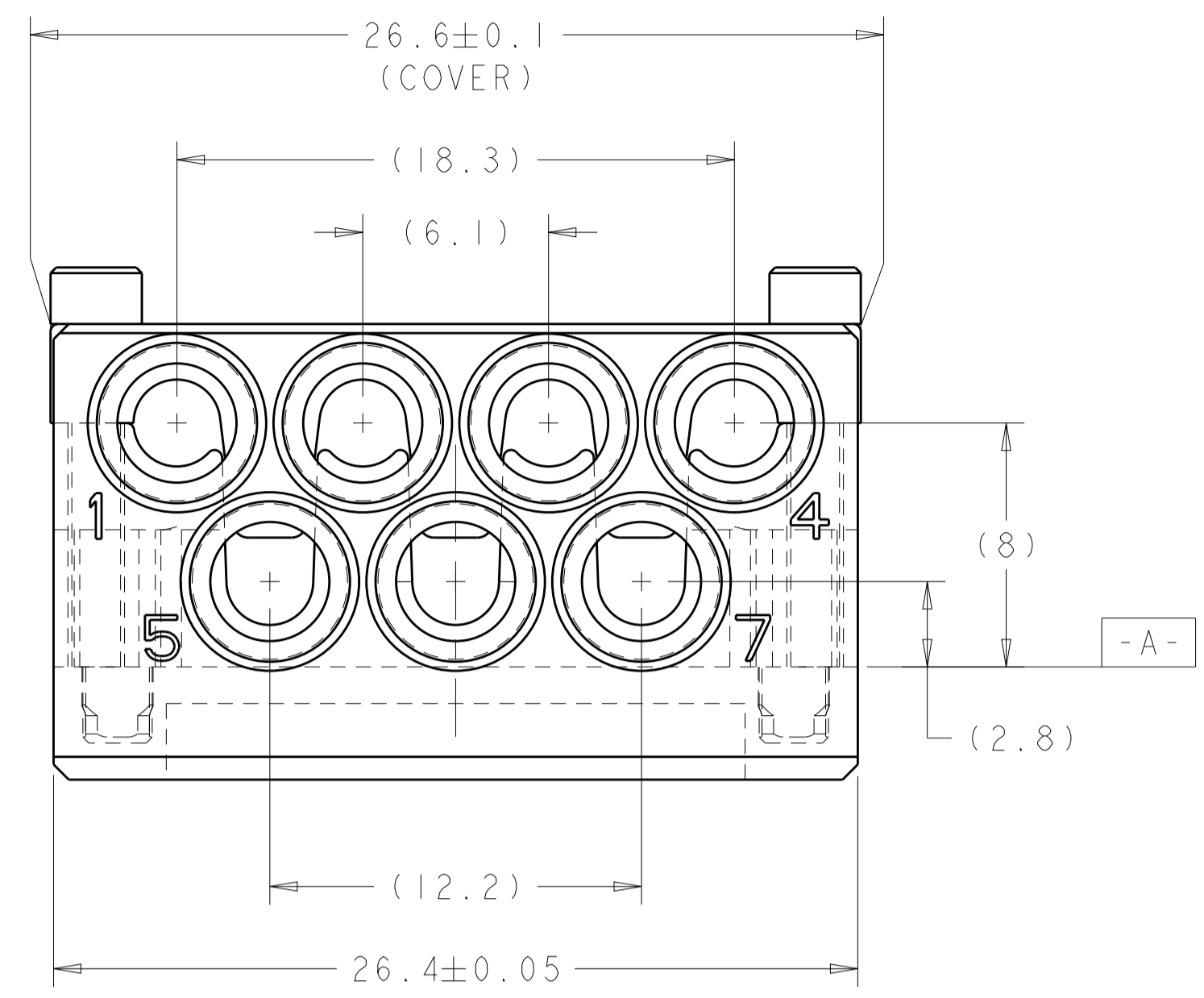


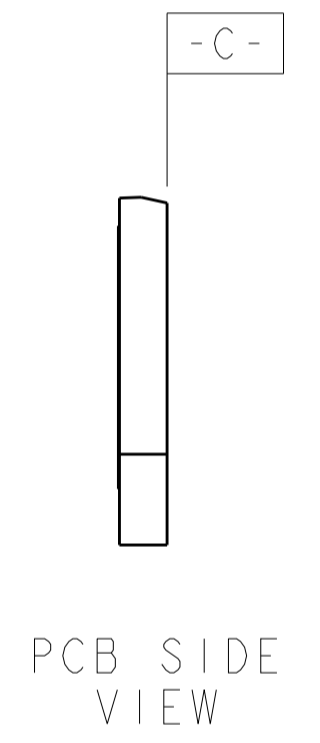
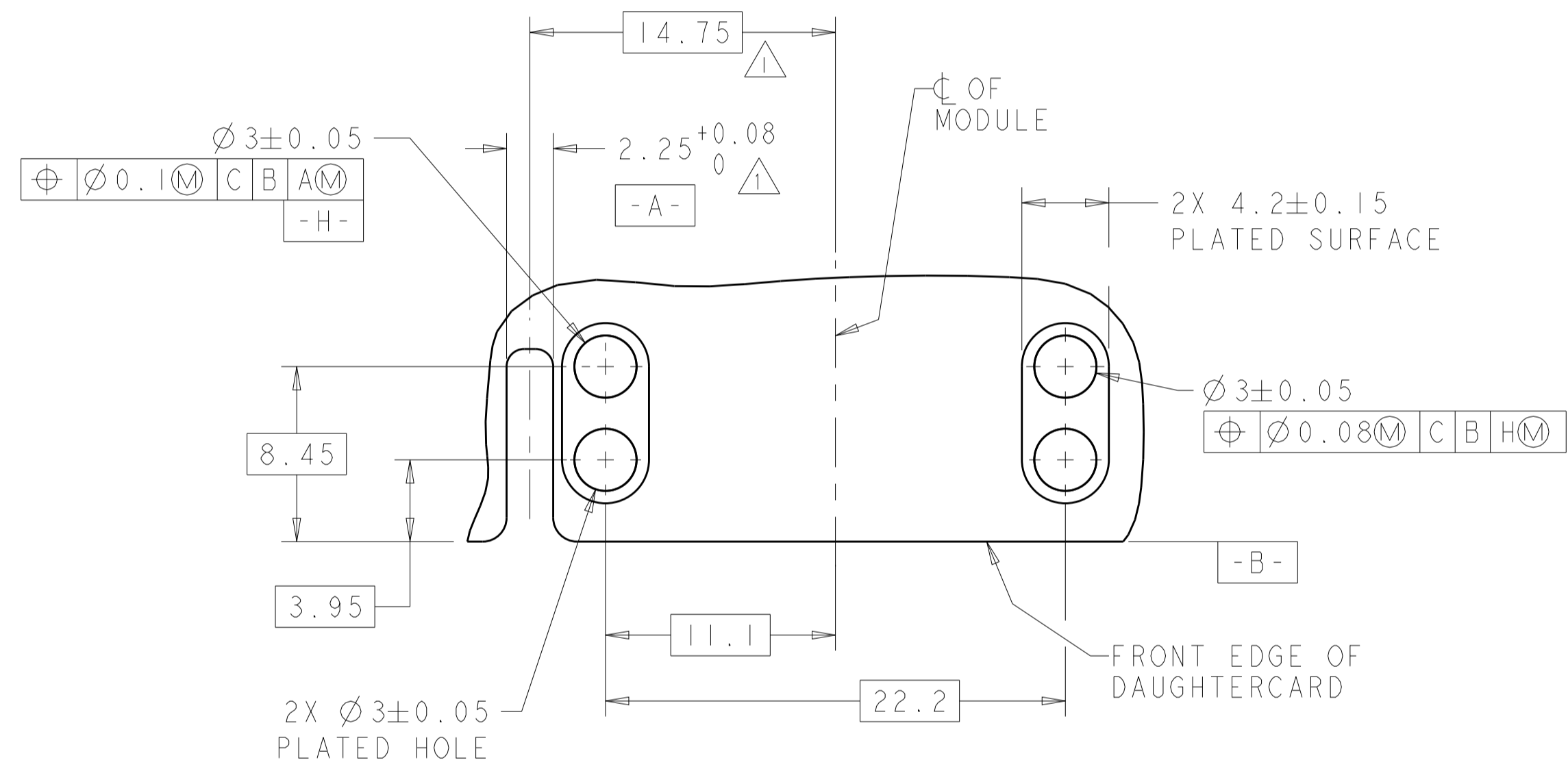
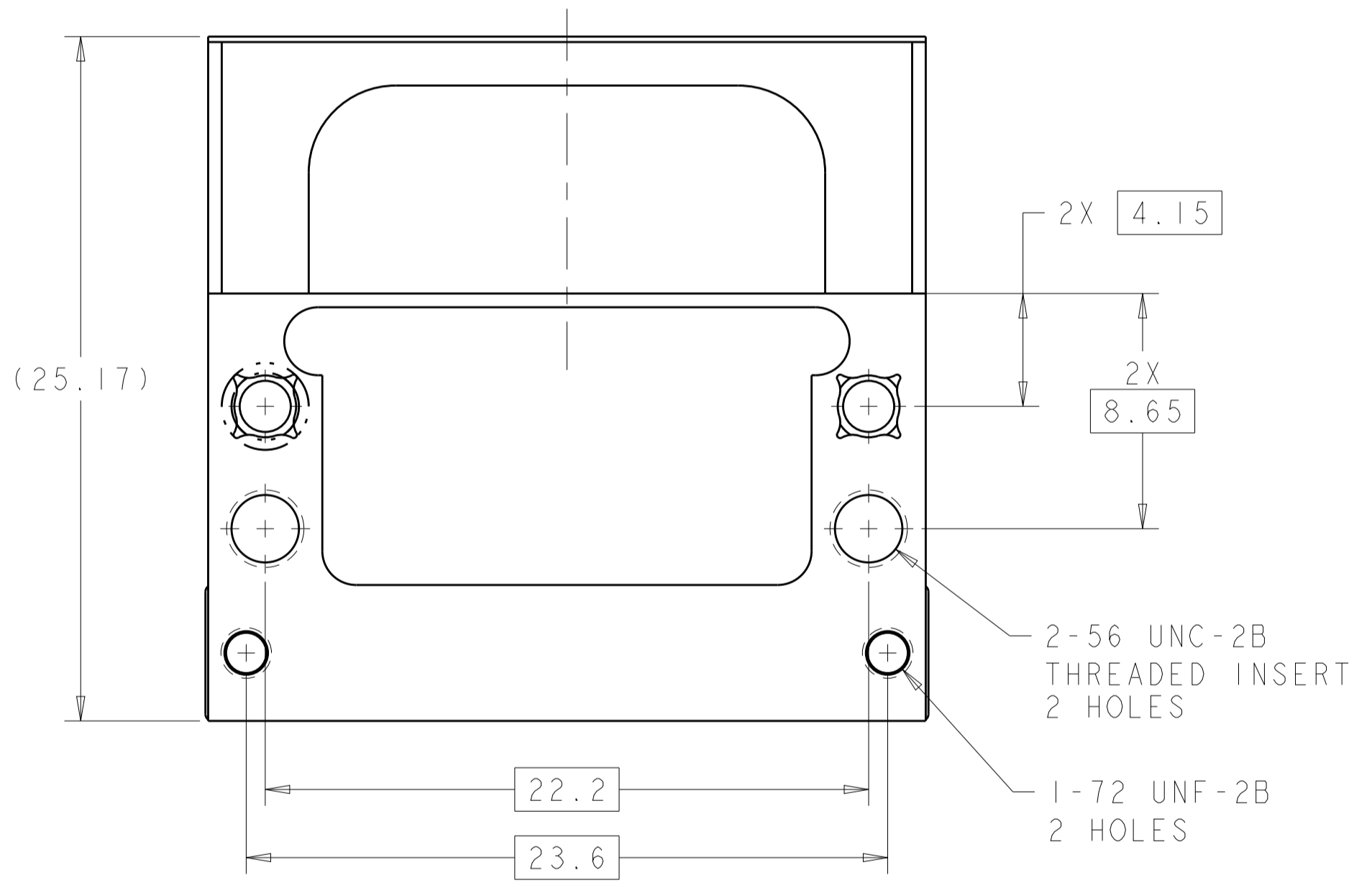
LOC	DIST	REVISIONS			
		REV	DATE	BY	APPV
A5	DF	A	11-16-12	CT	DH



1 THE 2.25 FEATURE, [-A-], IS A TYPICAL HSR FAMILY LOCATING FEATURE. IN OTHER APPLICATIONS OF THIS MODULE A DIFFERENT FEATURE MAY BE USED FOR ESTABLISHING CORRECT LOCATION. THE [14.75] DIMENSION MAY BE REPLACED WITH OTHER VALUES FOR LOCATING THIS MODULE IN DIFFERENT POCKETS OF VARIOUS HSR CONFIGURATIONS.

2 MATL: ALUMINUM PER ASTM-B-209. FINISH: ELECTROLESS NICKEL PER AMS-C-26074 CLASS 1.

3. PARTS SHIPPED UNASSEMBLED.



PCB LAYOUT FOR SMPM MODULE KIT, 2102272-1 SCALE 4:1

AS SHOWN	7	2102272-1
DESCRIPTION	MATERIAL AND FINISH	KIT NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT. DIMENSIONS: mm. TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ±, 1 PLC ±0.1, 2 PLC ±0.05, 3 PLC ±, 4 PLC ±, ANGLES ±. MATERIAL: SEE TABLE. FINISH: SEE TABLE. DATE: 09 JUL 2010. CHK: Brent D. Toth. CHNG: CHONG YI. APVD: CHONG YI. PRODUCT SPEC: APPLICATION SPEC. WEIGHT: Customer Drawing. SCALE: 5:1. SHEET 1 OF 1. REV A.

**STE** TE Connectivity

KIT, MODULE AND STRAIN RELIEF, 7 POSN, SMPM, PLUG, DAUGHTER CARD, HSR, UNSEALED

A100779C=2102272